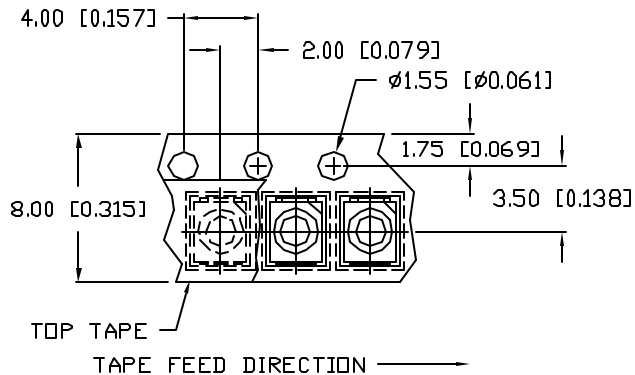
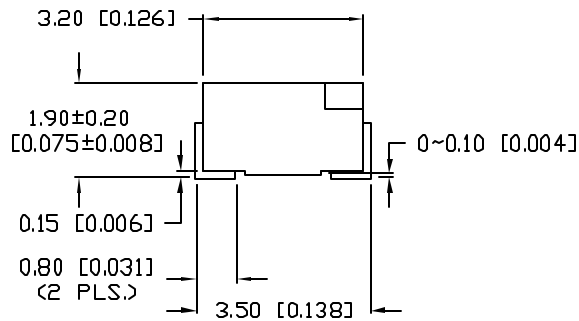
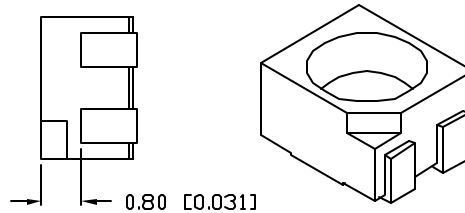
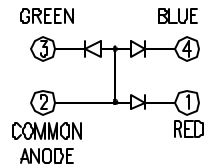
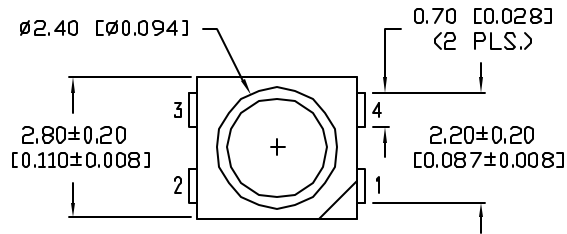
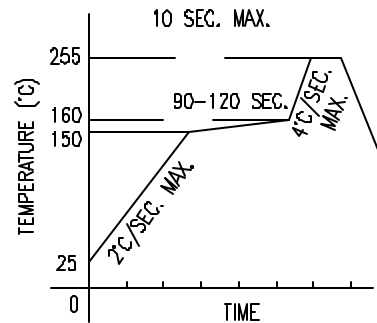


UNCONTROLLED DOCUMENT

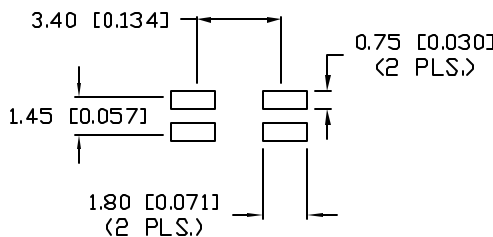


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



PART NUMBER		REV.
SML-LX2832SIUPUBTR		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11148.	2.8.05

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	RED	GREEN	BLUE	UNITS	TEST COND
PEAK WAVELENGTH	636	525	470	nm	
FORWARD VOLTAGE (TYP.)	2.0	3.5	3.5	V_f	
FORWARD VOLTAGE (MAX.)	2.6	4.0	4.0	V_f	
REVERSE VOLTAGE	5.0	5.0	5.0	V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY	200	100	60	mcd	$I_f=20\text{mA}$
VIEWING ANGLE	120	120	120	2x theta	
LED POSITION:	1	3	4		
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*	(R/G/B)	160/100/100	mA
STEADY CURRENT	(R/G/B)	30/25/30	mA
POWER DISSIPATION	(R/G/B)	120	mW
DERATE FROM 25°C	(R/G/B)	-1.2/-1.2/-2.0	mW/°C
OPERATING TEMP.		-25 TO +85	°C
STORAGE TEMP.		-30 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

1. THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), WLN=+0.00/-0.00, MAX.=+0.00/-0.00

REV.	PART NUMBER
A	SML-LX2832SIUPUBTR

2.8mm x 3.2mm SURFACE MOUNT WITH REFLECTOR CUP,
AlInGaP RED, ULTRA PURE GREEN, ULTRA SUPER BLUE,
WATER CLEAR LENS, TAPE AND REEL

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RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



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			SCALE: N/A